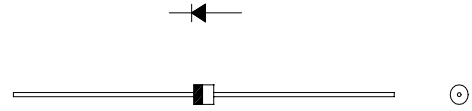


FRD Type :10ERA60

OUTLINE DRAWING

FEATURES

- * Miniature Size
- * Super Fast Recovery
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * 26mm and 52mm Inside Tape Spacing



Maximum Ratings

Approx Net Weight:0.17g

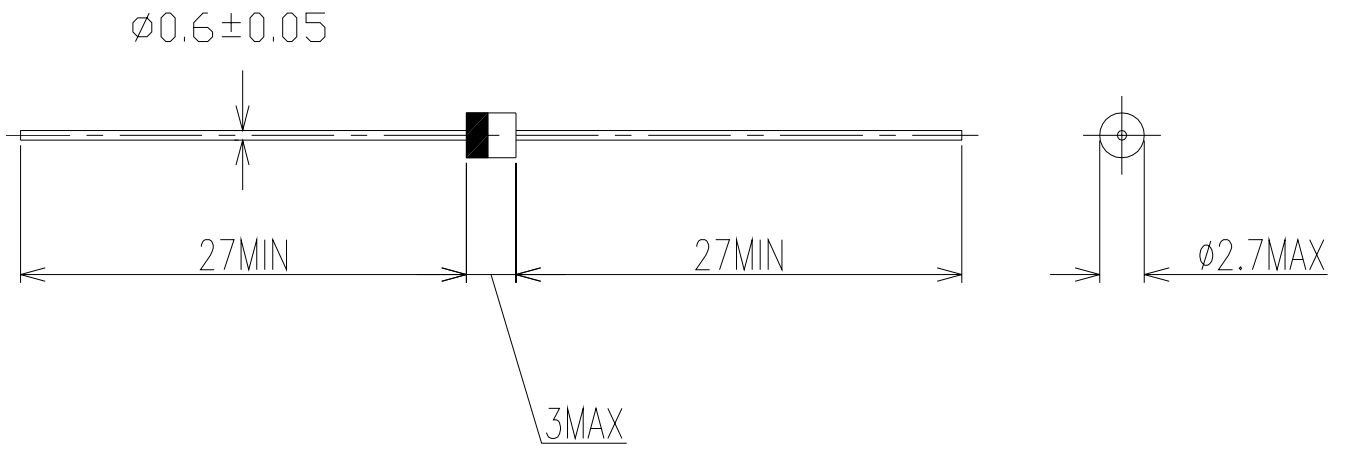
Rating	Symbol	10ERA60			Unit	
Repetitive Peak Reverse Voltage	V_{RRM}	600			V	
Average Rectified Output Current	-	I_O	1.0	$T_l=118^{\circ}\text{C}$	Half Sine Wave	A
			0.96	$T_a=26^{\circ}\text{C} *1$	Resistive Load	
RMS Forward Current	$I_{F(RMS)}$	1.57			A	
Surge Forward Current	I_{FSM}	30	Half Sine Wave,1cycle,Non-repetitive		A	
Operating JunctionTemperature Range	T_{jw}	- 40 to + 150			$^{\circ}\text{C}$	
Storage Temperature Range	T_{stg}	- 40 to + 150			$^{\circ}\text{C}$	

Electrical • Thermal Characteristics

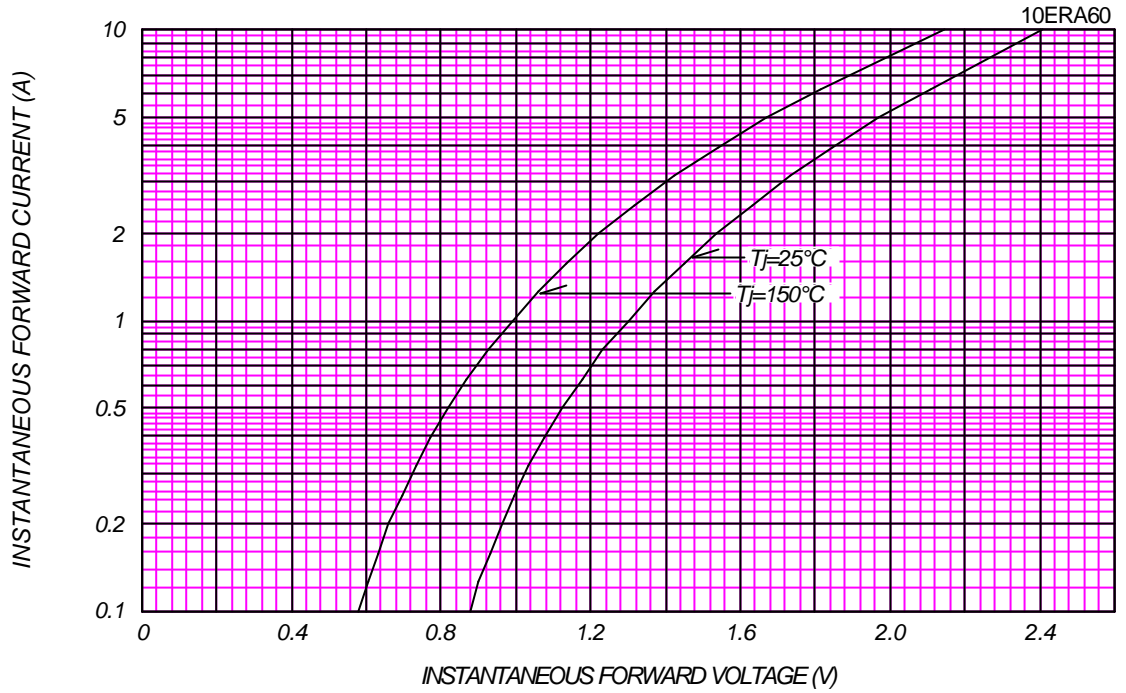
Characteristics	Symbol	Conditions	Min	Typ	Max	Unit
Peak Reverse Current	I_{RM}	$T_j=25^{\circ}\text{C}$, $V_{RM}= V_{RRM}$	-	-	10	μA
Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}\text{C}$, $I_{FM}= 1 \text{ A}$	-	-	1.30	V
Reverse Recovery Time	trr	$I_{FM}= 1 \text{ A}$, $-di/dt= 50 \text{ A}/\mu\text{s}$, $T_a=25^{\circ}\text{C}$	-	-	80	ns
Thermal Resistance	Rth(j-l)	Junction to Lead	-	-	23	$^{\circ}\text{C}/\text{W}$
	Rth(j-a)	Junction to Ambient *1	-	-	100	$^{\circ}\text{C}/\text{W}$

*1: Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm,Both Sides)
 T_l =Lead Temperature

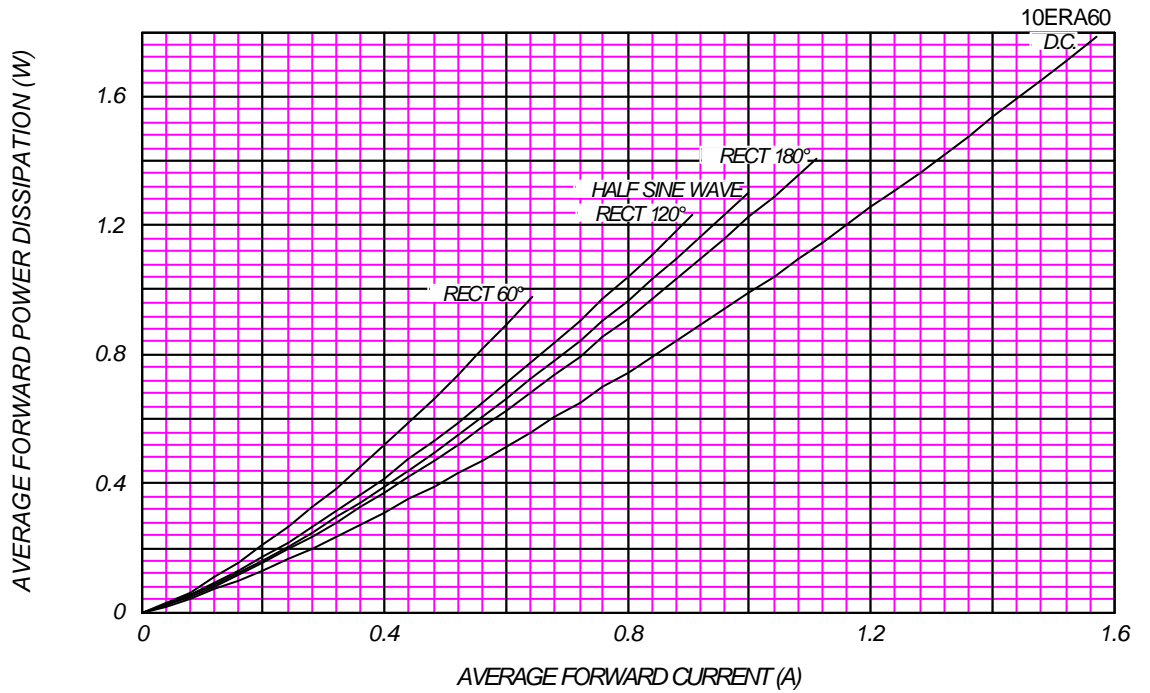
10ERA60 OUTLINE DRAWING (Dimensions in mm)

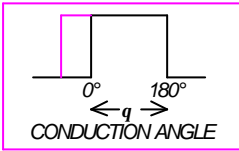


FORWARD CURRENT VS. VOLTAGE



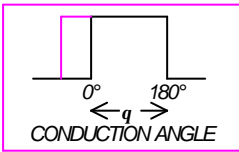
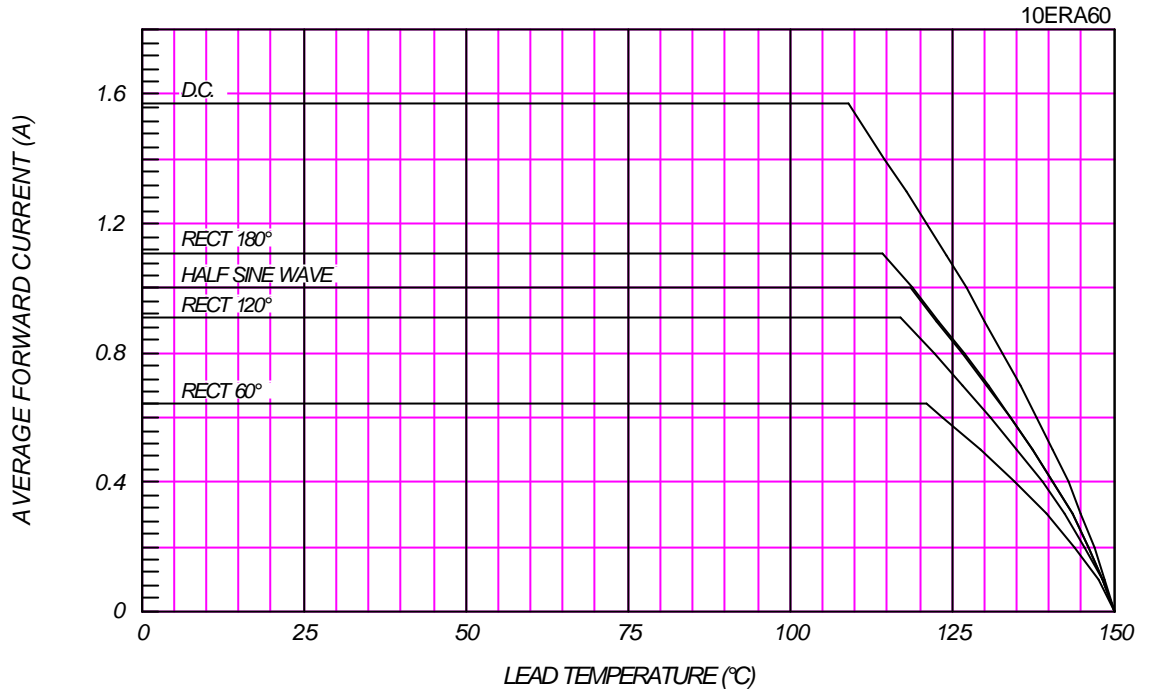
AVERAGE FORWARD POWER DISSIPATION





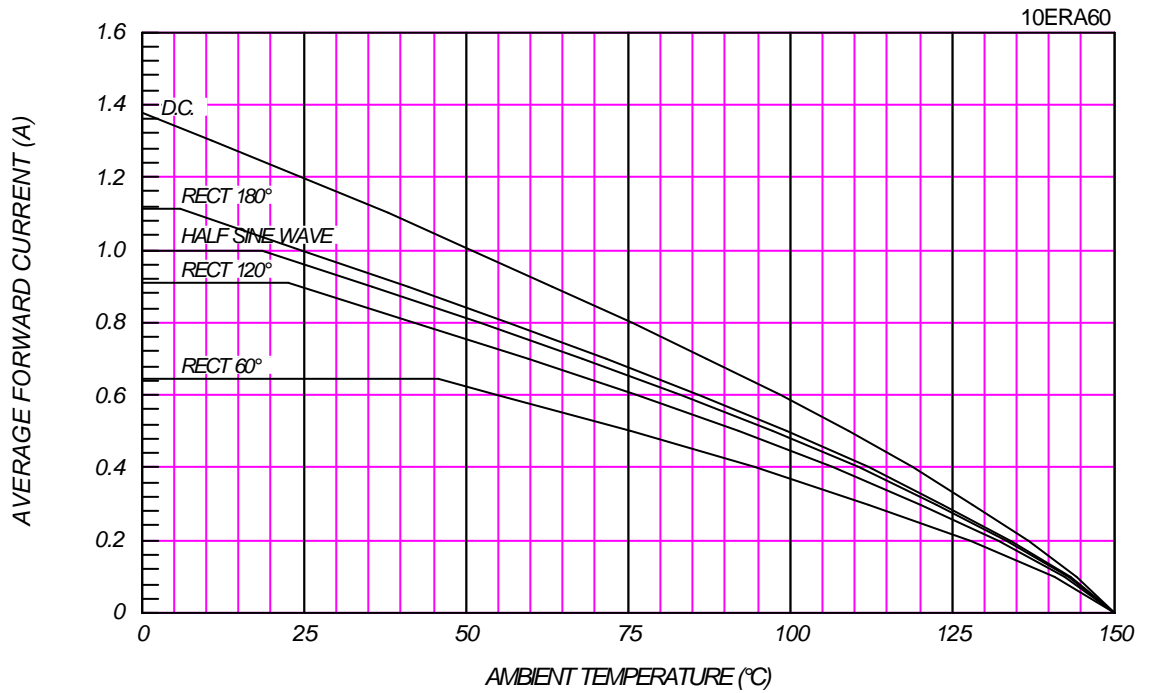
AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE

Without Fin or P.C. Board



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

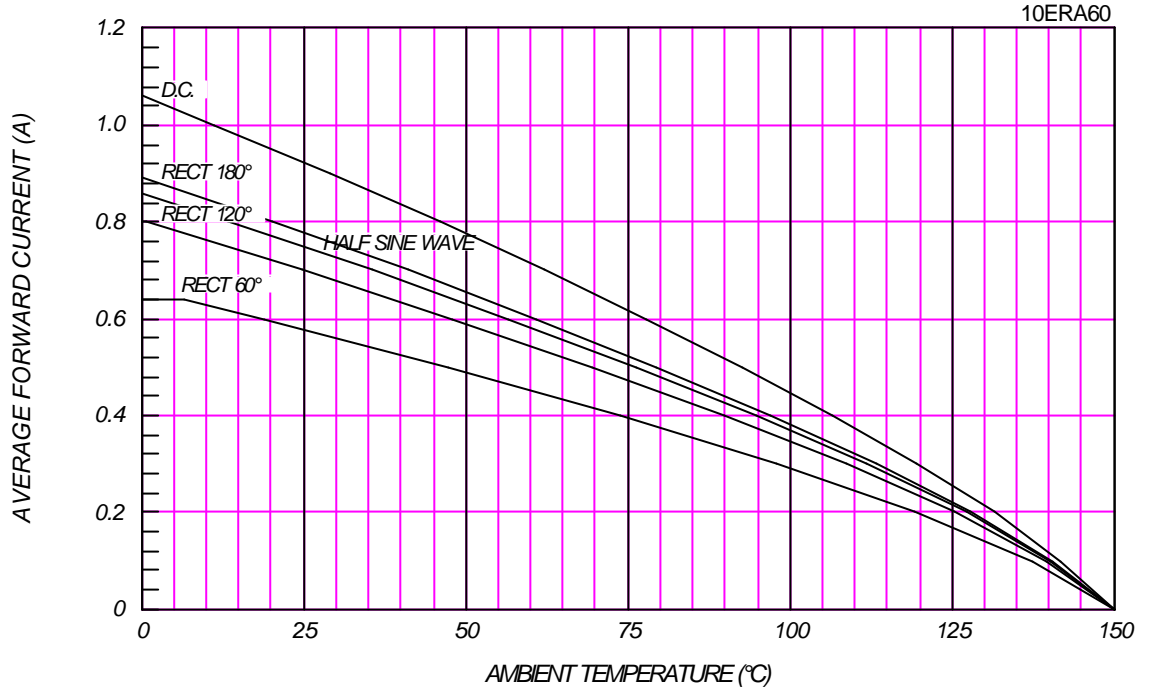
P.C. Board mounted (L=3mm, Print Land=7x7mm, Both Sides)





AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Without Fin or P.C. Board



SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, No Load

